## Fabrication of superconducting detectors for studying the Universe

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## What we can learn by using far-infrared (FIR) astronomical observatories

The age and origins of the Universe.

The presence of water in extra-solar planets.

Stellar formation and evolution.

Searches for dark matter.





## What we can learn by using x-ray astronomical observatories



- JETS HITTING SURROUNDING GAS AND HEATING IT.

Look for the presence of hot dark matter around metallic ions.

 JETS HITTING SURROUNDING GAS AND HEATING IT.

Study regions around and locate massive black holes.



#### Means of making these measurements: Focal plane detector arrays

- Light is focused onto the focal plane detector arrays via optics.
- Individual detector elements populate the focal plane -> good spatial resolution.
- A focal plane detector has a very small form factor, which allows for low hardware mass.
- A focal plane geometry facilitates integration with other components (e.g., antireflection coatings and backshorts).
- Focal plane array realization is highly dependent on advances in fabrication and packaging.

Pop-up bolometric detector array on the Atacama Cosmology Telescope (ACT).





#### Why use superconducting detectors?

 Operate at cryogenic temperature => Good signal to-noise

• High heat capacity => Large dynamic range

 Somewhat easy/inexpensive to set relevant parameters



## Transition edge sensors (TES)

- Bias a superconductor so that it is in the transition region of its R vs T curve.
- A small change in the TES temperature will cause its resistance to increase.
- This will cause the current flowing through the TES to decrease.
- The change in current is detected by a SQUID.



Steady state condition



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After absorption of energy



#### TES for x-ray instrumentation





### TES for FIR

- Radiation couples to antenna.
- Resistive absorber heats TES.
- Electron/phonon temperature difference dominates noise.
- The noise equivalent power (NEP) of these sensors is approaching the background-limited noise of the cosmic microwave background.



# Microwave kinetic inductance detectors (MKIDs)

Break a superconducting detector's Cooper pairs with incoming (sub-mm, FIR) radiation.

• This increases in the detector's kinetic inductance  $L_k$  and surface resistance  $R_s$ .

When the detector is integrated as part of a resonant circuit, the change in  $L_k$ ,  $R_s$  results in:

- A decrease in resonant frequency
- A decrease in power absorbed by the resonator

![](_page_9_Figure_6.jpeg)

![](_page_9_Picture_8.jpeg)

-10

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![](_page_10_Figure_6.jpeg)

![](_page_10_Picture_8.jpeg)

-10

#### MKIDs as far-infrared detectors

#### Antenna-coupled

![](_page_11_Picture_2.jpeg)

Incident power is coupled to antenna, which is then absorbed by a resistive(at that *f*) KID.

Absorber-coupled

![](_page_11_Picture_5.jpeg)

Incident power is coupled to broadband absorber which acts simultaneously as KID.

![](_page_11_Picture_7.jpeg)

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#### **Device Fabrication**

Physical vapor deposition systems

![](_page_13_Picture_2.jpeg)

For depositing thin dielectric and metal films on Si wafers

![](_page_13_Picture_4.jpeg)

Photoresist spinners and mask aligners

![](_page_14_Picture_2.jpeg)

#### For creating masks to pattern the thin films

![](_page_14_Picture_4.jpeg)

Plasma etchers and corrosive chemicals

![](_page_15_Picture_2.jpeg)

#### To etch the thin films as well as the silicon substrates

![](_page_15_Picture_4.jpeg)

Wafer bonders

![](_page_16_Picture_2.jpeg)

#### To bond Si wafers together

![](_page_16_Picture_4.jpeg)

Wire bonders

![](_page_17_Picture_2.jpeg)

#### To integrate detectors with readout electronics and/or amplifiers

![](_page_17_Picture_4.jpeg)

#### **Example of an MKID Fabrication Process**

![](_page_18_Figure_1.jpeg)

![](_page_18_Picture_2.jpeg)

#### Architecture of x-ray TES

![](_page_19_Figure_1.jpeg)

![](_page_19_Picture_2.jpeg)

#### Fabrication developments for x-ray TES: Cantilevered "mushroom" absorbers

![](_page_20_Picture_1.jpeg)

Au/Bi

\*A. Brown et al, J. Low Temp. Phys. (2008)

![](_page_20_Picture_3.jpeg)

#### Architecture of FIR TES

1 THz Antenna-Coupled Bolometric Transition-Edge Sensor (TES)

![](_page_21_Figure_2.jpeg)

### Fabrication developments for FIR TES: Novel ground plane and absorber materials

Novel microstructured Au thin films as ground plane material

Our Au films act very similar to perfect

electrical conductors.

Novel microstructured Bi thin films as THz absorbers

![](_page_22_Figure_3.jpeg)

IAE Bi; 5 K IAE Bi; RT TE Bi; RT 7 0 2 3 5 6

Frequency (THz)

8

Our Bi films act like purely resistive elements over a broad frequency range.

![](_page_22_Picture_7.jpeg)

\*A. Brown et al, AIP Conf. Proc. (2009)

#### Architecture of Absorber-Coupled MKID

![](_page_23_Figure_1.jpeg)

![](_page_23_Picture_2.jpeg)

#### Fabrication developments for Absorber-Coupled MKID: Novel fabrication methodology in which...

An entire camera can be fabricated on a single 1.5 micron thick Si membrane.

![](_page_24_Picture_2.jpeg)

There is a very small front-to-back misalignment, which results in low transmission line loss, without having to use front-to-back lithographic techniques.

![](_page_24_Picture_4.jpeg)

\*A. Brown et al, SPIE Conf. Proc. (2010)

![](_page_24_Picture_6.jpeg)

#### Architecture of Antenna-Coupled MKID

![](_page_25_Picture_1.jpeg)

Thin silicon membranes are never roughened.

![](_page_25_Picture_3.jpeg)

#### Fabrication developments for Absorber-Coupled MKID: Keep Si membrane smooth throughout fabrication

Roughening of Si during fabrication can introduce noise in the detectors.

Solution: Develop many different liftoff techniques in order to avoid having to etch the metals (Nb).

#### Liftoff involves:

- 1. Depositing liftoff material(s).
- 2. Patterning that material with a negative image of what is desired.
- 3. Depositing the desired material.
- 4. Selectively removing the liftoff material.

Novel liftoff process to pattern the Nb thin films used for the capacitors and transmission lines.

![](_page_26_Picture_9.jpeg)

![](_page_26_Picture_10.jpeg)

### Ancillary devices: Filters

#### Boxed microstrip lowpass filter

![](_page_27_Figure_2.jpeg)

Needed for ultrahigh sensitivity detector operation.

**Bandpass grill filter** 

![](_page_27_Picture_5.jpeg)

Needed for rejecting out-of-band thermal noise

![](_page_27_Picture_7.jpeg)

### Summary

 Superconducting detectors offer unparalleled means of making astronomical/cosmological observations.

 Fabrication of these detectors is somewhat unconventional; however, a lot of novel condensed matter physics/materials scientific discoveries and semiconductor fabrication processes can be generated in making these devices.

![](_page_28_Picture_3.jpeg)

### Acknowledgments

- NASA GSFC:
  - Code 553 Detector Systems Branch
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  - Code 693 Planetary Instruments Laboratory

![](_page_29_Picture_9.jpeg)